

# **30V N-Channel Trench MOSFET(Preliminary)**

General Description			Product Summary			
<ul> <li>Trench Power technology</li> <li>Low Capacitance</li> <li>Ultra low Gate Charge</li> <li>Optimized for fast-switching applications</li> </ul>			$V_{DS}$ 30V $I_D$ (at $V_{GS}$ =10V)         60A $R_{DS(ON)}$ (at $V_{GS}$ =10V)         < 5.8m $\Omega$ $R_{DS(ON)}$ (at $V_{GS}$ =4.5V)         < 8.8m $\Omega$			
<ul> <li>Applications</li> <li>Synchronous Rectification in</li> <li>Isolated DC/DC Converters in</li> </ul>			100% UIS Tested 100% DVDS Tested			
DFN3.	<sup>3x3.3</sup>	Pin 1	G G G S S			
Part Number	Packa	іде Туре	Form	Marking		
TTG60N03QTC	DFN	3.3x3.3	Tape & Reel	60N03QTC		
110001000010			Tapo a ricor			
Absolute Maximum Ra	tings (T <sub>A</sub> =2	5ºC unless o	therwise noted)			
Absolute Maximum Ra Parameter	tings (T <sub>A</sub> =2	5ºC unless o	therwise noted) Maximum	Units		
Absolute Maximum Ra Parameter Drain-Source Voltage	tings (T <sub>A</sub> =2	5°C unless o Symbol V <sub>DS</sub>	therwise noted) Maximum 30	Units V		
Absolute Maximum Ra Parameter		5ºC unless o	therwise noted) Maximum 30 ±20	Units		
Absolute Maximum Ra Parameter Drain-Source Voltage	T <sub>c</sub> =25°C	5°C unless o Symbol V <sub>DS</sub>	therwise noted)         Maximum       30         ±20       17	Units V		
Absolute Maximum Ra Parameter Drain-Source Voltage Gate-Source Voltage		5°C unless o Symbol V <sub>DS</sub> V <sub>GS</sub>	therwise noted) Maximum 30 ±20	Units V V		
Absolute Maximum Ra Parameter Drain-Source Voltage Gate-Source Voltage Continuous Drain Current <sup>B</sup>	T <sub>c</sub> =25°C	5°C unless o Symbol V <sub>DS</sub> V <sub>GS</sub> I <sub>D</sub>	therwise noted) Maximum 30 ±20 17 17	Units V V A		
Absolute Maximum Ra Parameter Drain-Source Voltage Gate-Source Voltage Continuous Drain Current B Pulsed Drain Current A	T <sub>c</sub> =25°C	5°C unless o Symbol V <sub>DS</sub> V <sub>GS</sub> I <sub>D</sub> I <sub>DM</sub> I <sub>AS</sub>	therwise noted)         Maximum       30         30       ±20         17       17         17       180	Units V V A A		
Absolute Maximum Ra         Parameter         Drain-Source Voltage         Gate-Source Voltage         Continuous Drain Current         B         Pulsed Drain Current         Avalanche Current         A         Single Pulse Avalanche Energy	$T_{c} = 25^{\circ}C$ $T_{c} = 100^{\circ}C$ L = 0.3mH <sup>A</sup>	5°C unless o Symbol V <sub>DS</sub> V <sub>GS</sub> I <sub>D</sub> I <sub>DM</sub> I <sub>AS</sub> E <sub>AS</sub>	therwise noted)         Maximum       30         30       ±20         17       17         17       18         18       18	Units V V A A A A		
Absolute Maximum Ra         Parameter         Drain-Source Voltage         Gate-Source Voltage         Continuous Drain Current         B         Pulsed Drain Current         Avalanche Current	$     T_{C} = 25^{\circ}C     T_{C} = 100^{\circ}C $	5°C unless o Symbol V <sub>DS</sub> V <sub>GS</sub> I <sub>D</sub> I <sub>DM</sub> I <sub>AS</sub>	therwise noted)         Maximum       30         30       ±20         17       17         17       180         18       48.6	Units V V A A A A M		
Absolute Maximum Ra         Parameter         Drain-Source Voltage         Gate-Source Voltage         Continuous Drain Current         B         Pulsed Drain Current         Avalanche Current         A         Single Pulse Avalanche Energy	$ \begin{array}{c} T_{C} = 25^{\circ}C \\ T_{C} = 100^{\circ}C \\ \end{array} $ $ \begin{array}{c} L = 0.3mH & ^{A} \\ T_{C} = 25^{\circ}C \\ \hline T_{C} = 100^{\circ}C \\ \end{array} $	5°C unless o Symbol V <sub>DS</sub> V <sub>GS</sub> I <sub>D</sub> I <sub>DM</sub> I <sub>AS</sub> E <sub>AS</sub>	therwise noted)         Maximum       30         30       ±20         17       17         17       180         18       48.6         46.8       46.8	Units V V A A A A M J W		
Absolute Maximum Ra Parameter Drain-Source Voltage Gate-Source Voltage Continuous Drain Current <sup>B</sup> Pulsed Drain Current <sup>A</sup> Avalanche Current <sup>A</sup> Single Pulse Avalanche Energy Power Dissipation <sup>C</sup>	$ \begin{array}{c} T_{C} = 25^{\circ}C \\ T_{C} = 100^{\circ}C \\ \end{array} $ $ \begin{array}{c} L = 0.3mH & ^{A} \\ T_{C} = 25^{\circ}C \\ \hline T_{C} = 100^{\circ}C \\ \end{array} $	5°C unless o Symbol V <sub>DS</sub> V <sub>GS</sub> I <sub>D</sub> I <sub>DM</sub> I <sub>AS</sub> E <sub>AS</sub> P <sub>D</sub>	therwise noted)         Maximum         30         ±20         17         17         18         48.6         46.8         23.4	Units V V A A A A M J W W		
Absolute Maximum Ra         Parameter         Drain-Source Voltage         Gate-Source Voltage         Continuous Drain Current         Pulsed Drain Current         Avalanche Current         Aingle Pulse Avalanche Energy         Power Dissipation         C         Junction and Storage Temperation	$ \begin{array}{c} T_{C} = 25^{\circ}C \\ T_{C} = 100^{\circ}C \\ \end{array} $ $ \begin{array}{c} L = 0.3mH & ^{A} \\ T_{C} = 25^{\circ}C \\ \hline T_{C} = 100^{\circ}C \\ \end{array} $	5°C unless o Symbol V <sub>DS</sub> V <sub>GS</sub> I <sub>D</sub> I <sub>DM</sub> I <sub>AS</sub> E <sub>AS</sub> P <sub>D</sub>	therwise noted)         Maximum         30         ±20         17         17         18         48.6         46.8         23.4	Units V V A A A A M J W W		
Absolute Maximum Ra         Parameter         Drain-Source Voltage         Gate-Source Voltage         Continuous Drain Current         B         Pulsed Drain Current         Avalanche Current         A         Single Pulse Avalanche Energy         Power Dissipation         C         Junction and Storage Temperatu         Thermal Characteristics	$ \begin{array}{c} T_{C} = 25^{\circ}C \\ T_{C} = 100^{\circ}C \\ \end{array} $ $ \begin{array}{c} L = 0.3mH & ^{A} \\ T_{C} = 25^{\circ}C \\ \hline T_{C} = 100^{\circ}C \\ \end{array} $	5°C unless o Symbol V <sub>DS</sub> V <sub>GS</sub> I <sub>D</sub> I <sub>DM</sub> I <sub>AS</sub> E <sub>AS</sub> P <sub>D</sub> T <sub>J</sub> , T <sub>STG</sub>	therwise noted)         Maximum         30         ±20         17         17         18         48.6         46.8         23.4         -55 to 175	Units V V A A A A M J W W W V C		



Electrical Characteristics(T <sub>J</sub> =25°C unless otherwise noted)								
Sumhal Deservation			Value					
Symbol	Parameter	Conditions		Min	Тур	Max	- Units	
STATIC P	ARAMETERS					-		
$BV_{DSS}$	Drain-Source Breakdown Voltage	I <sub>D</sub> =250µA,V <sub>GS</sub> =0V		30			V	
I <sub>DSS</sub> Zero Gate Voltage Drain Current		T <sub>J</sub> =25°C			1			
	Zero Gate Voltage Drain Current	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V	T <sub>J</sub> =125°C			100	- μΑ	
I <sub>GSS</sub>	Gate-Body Leakage Current	$V_{DS}=0V, V_{GS}=\pm 20V$				±100	nA	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250µA		1	1.6	2	V	
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =30A			4.8	5.8	mΩ	
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =4.5V, I <sub>D</sub> =30A			7.5	8.8	mΩ	
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =20A			29		S	
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =30A, V <sub>GS</sub> =0V				1	V	
I <sub>S</sub>	Maximum Body-Diode Continuous Curre	rent <sup>B</sup>				17	А	
DYNAMIC	PARAMETERS							
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =15V, f =1MH <sub>Z</sub>			855		pF	
C <sub>oss</sub>	Output Capacitance				230			
C <sub>rss</sub>	Reverse Transfer Capacitance				124			
R <sub>g</sub>	Gate Resistance	f =1MH <sub>z</sub>			7		Ω	
SWITCHIN	NG PARAMETERS							
Q <sub>g</sub> (10V)	Total Gate Charge	V <sub>GS</sub> =10V,V <sub>DS</sub> =15V, I <sub>D</sub> =20A			17.5		nC	
Q <sub>g</sub> (4.5V)	Total Gate Charge				9.2			
Q <sub>gs</sub>	Gate Source Charge				2.3			
$Q_{gd}$	Gate Drain Charge				4.5			
t <sub>D(on)</sub>	Turn-On Delay Time	$V_{GS} = 10V, V_{DS} = 15V, I_{D} = 20A, R_{G} = 1.6\Omega$			32		- ns	
t <sub>r</sub>	Turn-On Rise Time				3.6			
T <sub>D(off)</sub>	Turn-Off Delay Time				53			
t <sub>f</sub>	Turn-Off Fall Time				7.3			
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> =20A, di/dt =100A/μs			43.3		ns	
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge				23.7		nC	

A. Single pulse width limited by maximum junction temperature.

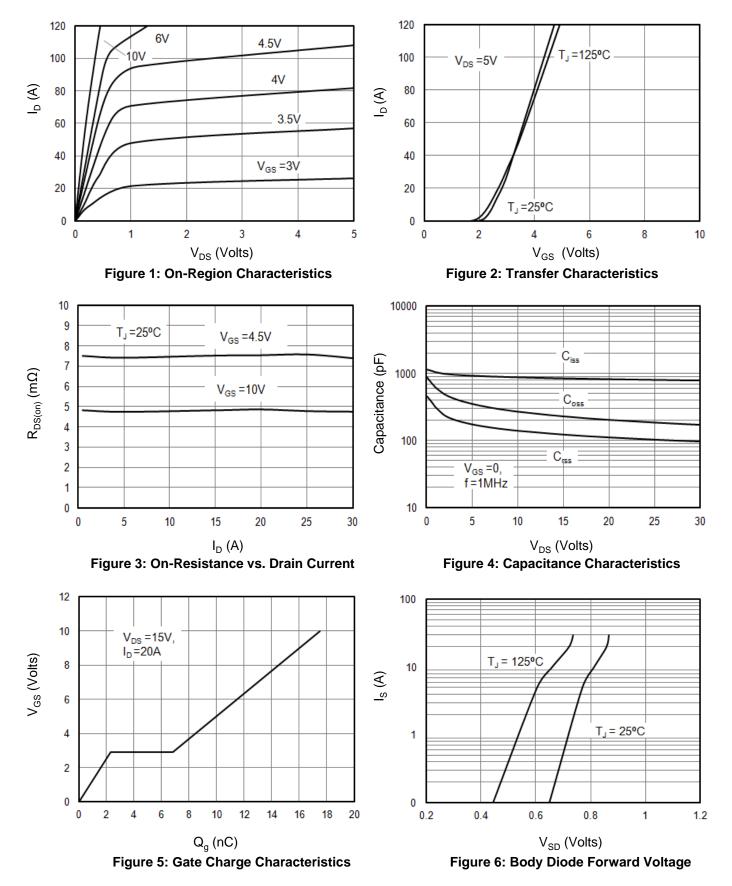
B. The maximum current rating is package limited.

C. The power dissipation  $P_D$  is based on  $T_{J(MAX)} = 175^{\circ}$ C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.



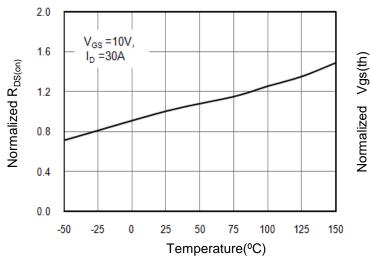


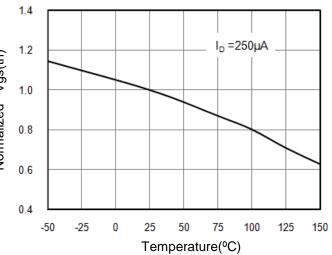
### TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

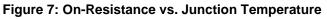


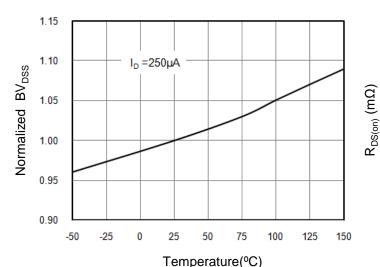


#### TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

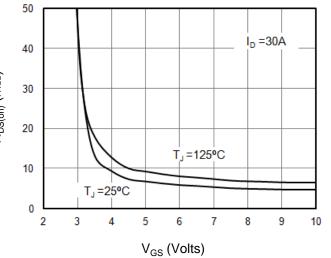












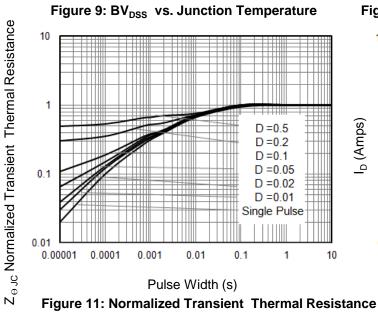
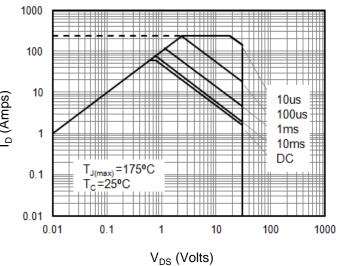
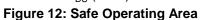
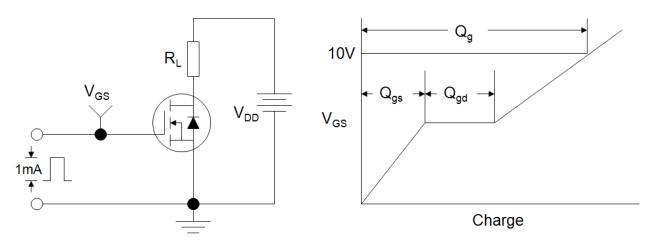


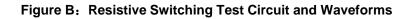
Figure 10: On-Resistance vs. Gate-Source Voltage











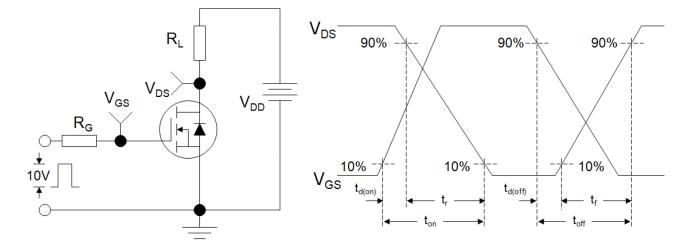
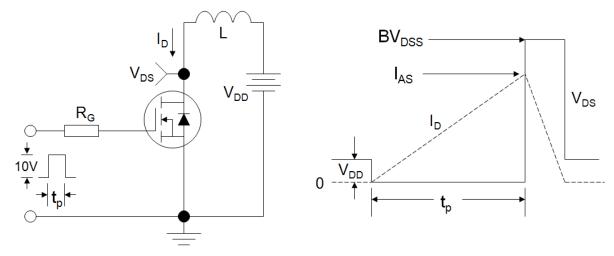
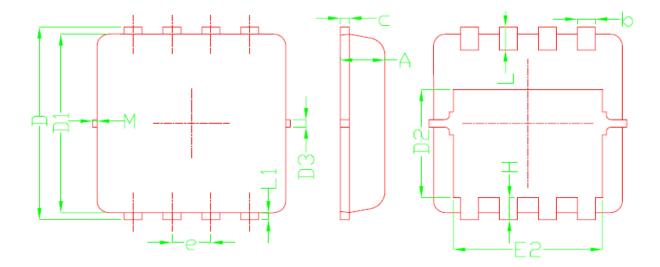


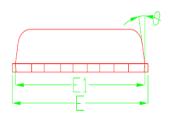
Figure C: Unclamped Inductive Switching (UIS) Test Circuit and Waveforms

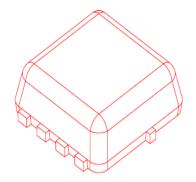


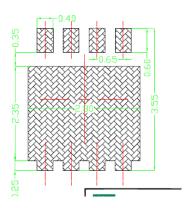


DFN 3.3x3.3









an mor	DIMENSIONAL REQMTS					
SYMBOL	MIN	NOM	MAX			
A	0.70	0.75	0.80			
Ь	0.25	0.30	0.35			
С	0.10	0.15	0.25			
D	3.25	3.35	3.45			
DI	3.00	3.10	3.20			
D2	1.78	1.88	1.98			
D3		0.13				
Ε	3.20	3.30	3.40			
EI	3.00	3.15	3.20			
E2	2.39	2.49	2.59			
е	0.65BSC					
H	0.30	0.39	0.50			
L	0.30	0.40	0.50			
LI		0.13				
$\theta$		10°	12°			
M	*	*	0.15			
* Not specified						



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